

## ●HSOP-8N Power Dissipation

Power dissipation data for the HSOP-8N is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

### 1. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board Dimensions: For a 4-layer PCB measuring 76.2mm

×114.3mm (approximately 8700mm<sup>2</sup> on one side)

The copper foil areas are as follows.

1st layer: No copper foil (For signal layer)

2nd layer: 74.2mm x 74.2mm (Connected to heat sink)

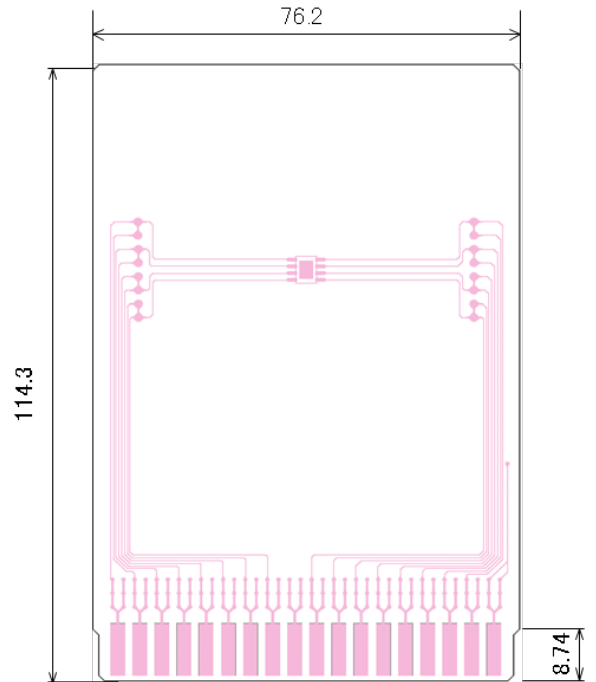
3rd layer: 74.2mm x 74.2mm (not connected to heat sink)

4th layer: No copper foil (For signal layer)

Material: Glass Epoxy (FR-4)

Thickness: 1.6mm

Through-hole: φ0.3mm

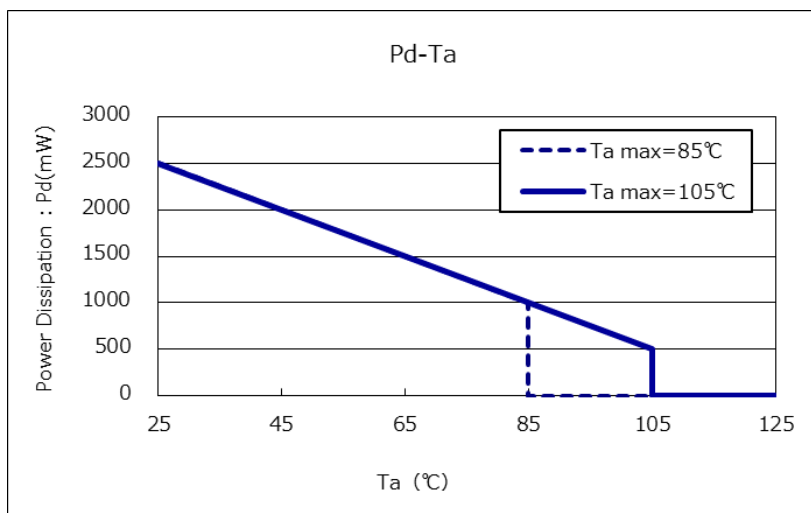


Evaluation Board Layout (Unit:mm)

### 2. Power Dissipation vs. Ambient Temperature

Board Mount (T<sub>imax</sub>=150°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)		Thermal Resistance (°C/W)
	Ta max=125°C	Ta max=150°C	
25	2500	2500	40.00
85	1000	1000	
105	0	500	
125	0	0	



**●HSOP-8N Power Dissipation ※Tjmax=150°C**

Power dissipation data for the HSOP-8N is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

**1. Measurement Condition (Reference data)**

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board Dimensions: For a 4-layer PCB measuring 76.2mm x 114.3mm (approximately 8700mm<sup>2</sup> on one side)

The copper foil areas are as follows.

1st layer: No copper foil (For signal layer)

2nd layer: 74.2mm x 74.2mm (Connected to heat sink)

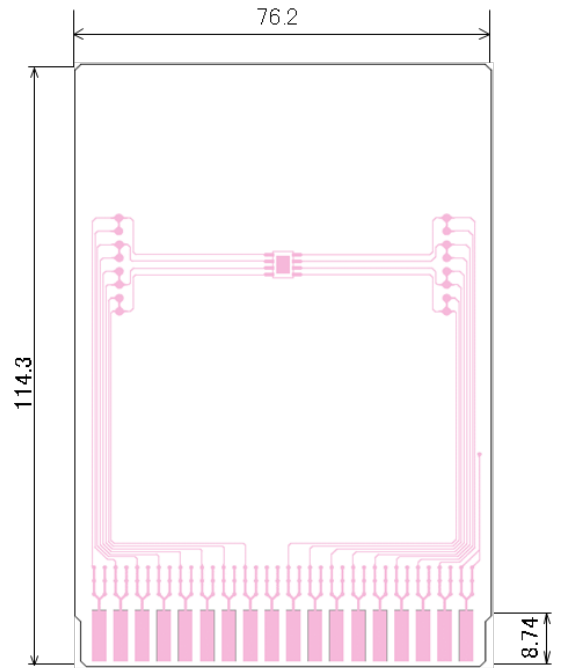
3rd layer: 74.2mm x 74.2mm (not connected to heat sink)

4th layer: No copper foil (For signal layer)

Material: Glass Epoxy (FR-4)

Thickness: 1.6mm

Through-hole: φ0.3mm



Evaluation Board Layout (Unit:mm)

**2. Power Dissipation vs. Ambient Temperature**

Board Mount ( Tjmax=150°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)		Thermal Resistance (°C/W)
	Ta max=125°C	Ta max=150°C	
25	3125	3125	40.00
125	625	625	
150	0	0	

